

■ Plasma Reactor / Cleaner



▶ Standard Type

- Used for Ashing, etching, dry cleaning for semiconductors, new material and in many industrial fields.
- Compact design, with a small size RF generator.

▶ System Specifications

Model	PR300	PR301	PR500	PR510	PR1000
Method	Barred type of direct plasma (DP)				
High frequency output	300W variable(100W×3ch)	Max. 300W	Max. 500W		Max. 1000W
Oscillating frequency	13.56 MHz				
Reaction chamber	Made of super hard glass, $\phi 64 \times 160 \text{mm} \times 3$	Made of pyrex glass, $\phi 118 \times 160 \text{mm}$	Made of quarts, $\phi 215 \times 305 \text{mm}$		Made of quarts, $\phi 400 \times 500 \text{mm}$
External dimension	438×520×556	438×520×656	438×520×760		700×820×1,600



▶ High Performance Type

- Settings programmable through dedicated.
- LCD touch panel display.
- CE certified. (PDC610 only)

▶ System Specifications

Model	PDC200	PDC210	PDC510	PDC610
Plasma mode	RIE (DP : option)			
Stage size(mm)	250(W)×170(D)		400(W)×200(D)	250(W)×210(D)
Aluminum chamber(mm)	400(W)×250(D)×150(H)		500×300×200	350×270×300
RF output power	Max. 300W		Max. 500W	Max. 600W
Oscillating frequency	13.56 MHz (Quarts oscillator)			